Microchip Technology - DSPIC33FJ128MC708T-I/PT Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	69
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 18x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj128mc708t-i-pt

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name	Pin Type	Buffer Type	Description
AN0-AN31	I	Analog	Analog input channels.
AVDD	P	P	Positive supply for analog modules. This pin must be connected at all times.
AVSS	P	P	Ground reference for analog modules.
CLKI CLKO	I O	ST/CMOS —	External clock source input. Always associated with OSC1 pin function. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
CN0-CN23	I	ST	Input change notification inputs. Can be software programmed for internal weak pull-ups on all inputs.
C1RX C1TX C2RX C2TX	I O I O	ST — ST —	ECAN1 bus receive pin. ECAN1 bus transmit pin. ECAN2 bus receive pin. ECAN2 bus transmit pin.
PGED1 PGEC1 PGED2 PGEC2 PGED3 PGEC3	I/O I I/O I I/O I	ST ST ST ST ST ST	Data I/O pin for programming/debugging communication channel 1. Clock input pin for programming/debugging communication channel 1. Data I/O pin for programming/debugging communication channel 2. Clock input pin for programming/debugging communication channel 2. Data I/O pin for programming/debugging communication channel 3. Clock input pin for programming/debugging communication channel 3.
IC1-IC8	I	ST	Capture inputs 1 through 8.
INDX QEA QEB UPDN	I I I O	ST ST ST CMOS	Quadrature Encoder Index Pulse input. Quadrature Encoder Phase A input in QEI mode. Auxiliary Timer External Clock/Gate input in Timer mode. Quadrature Encoder Phase A input in QEI mode. Auxiliary Timer External Clock/Gate input in Timer mode. Position Up/Down Counter Direction State.
INT0 INT1 INT2 INT3 INT4	I I I I I	ST ST ST ST ST	External interrupt 0. External interrupt 1. External interrupt 2. External interrupt 3. External interrupt 4.
$\overline{\text{FLTA}}$ $\overline{\text{FLTB}}$ PWM1L PWM1H PWM2L PWM2H PWM3L PWM3H PWM4L PWM4H	I I O O O O O O O O	ST ST — — — — — — — —	PWM Fault A input. PWM Fault B input. PWM 1 low output. PWM 1 high output. PWM 2 low output. PWM 2 high output. PWM 3 low output. PWM 3 high output. PWM 4 low output. PWM 4 high output.
$\overline{\text{MCLR}}$	I/P	ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
OCFA OCFB OC1-OC8	I I O	ST ST —	Compare Fault A input (for Compare Channels 1, 2, 3 and 4). Compare Fault B input (for Compare Channels 5, 6, 7 and 8). Compare outputs 1 through 8.
OSC1 OSC2	I I/O	ST/CMOS —	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.

Legend: CMOS = CMOS compatible input or output Analog = Analog input P = Power
ST = Schmitt Trigger input with CMOS levels O = Output I = Input

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Type	Buffer Type	Description
RA0-RA7 RA9-RA10 RA12-RA15	I/O I/O I/O	ST ST ST	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	PORTB is a bidirectional I/O port.
RC1-RC4 RC12-RC15	I/O I/O	ST ST	PORTC is a bidirectional I/O port.
RD0-RD15	I/O	ST	PORTD is a bidirectional I/O port.
RE0-RE9	I/O	ST	PORTE is a bidirectional I/O port.
RF0-RF8 RF12-RF13	I/O	ST	PORTF is a bidirectional I/O port.
RG0-RG3 RG6-RG9 RG12-RG15	I/O I/O I/O	ST ST ST	PORTG is a bidirectional I/O port.
SCK1 SDI1 SDO1 SS1 SCK2 SDI2 SDO2 SS2	I/O I O I/O I/O I O I/O	ST ST — ST ST ST — ST	Synchronous serial clock input/output for SPI1. SPI1 data in. SPI1 data out. SPI1 slave synchronization or frame pulse I/O. Synchronous serial clock input/output for SPI2. SPI2 data in. SPI2 data out. SPI2 slave synchronization or frame pulse I/O.
SCL1 SDA1 SCL2 SDA2	I/O I/O I/O I/O	ST ST ST ST	Synchronous serial clock input/output for I2C1. Synchronous serial data input/output for I2C1. Synchronous serial clock input/output for I2C2. Synchronous serial data input/output for I2C2.
SOSCI SOSCO	I O	ST/CMOS —	32.768 kHz low-power oscillator crystal input; CMOS otherwise. 32.768 kHz low-power oscillator crystal output.
TMS TCK TDI TDO	I I I O	ST ST ST —	JTAG Test mode select pin. JTAG test clock input pin. JTAG test data input pin. JTAG test data output pin.
T1CK T2CK T3CK T4CK T5CK T6CK T7CK T8CK T9CK	I I I I I I I I I	ST ST ST ST ST ST ST ST ST	Timer1 external clock input. Timer2 external clock input. Timer3 external clock input. Timer4 external clock input. Timer5 external clock input. Timer6 external clock input. Timer7 external clock input. Timer8 external clock input. Timer9 external clock input.
U1CTS U1RTS U1RX U1TX U2CTS U2RTS U2RX U2TX	I O I O I O I O	ST — ST — ST — ST —	UART1 clear to send. UART1 ready to send. UART1 receive. UART1 transmit. UART2 clear to send. UART2 ready to send. UART2 receive. UART2 transmit.
VDD	P	—	Positive supply for peripheral logic and I/O pins.
VCAP/VDDCORE	P	—	CPU logic filter capacitor connection.

Legend: CMOS = CMOS compatible input or output Analog = Analog input P = Power
ST = Schmitt Trigger input with CMOS levels O = Output I = Input

NOTES:

FIGURE 4-5: DATA MEMORY MAP FOR dsPIC33FJXXXMCX06/X08/X10 DEVICES WITH 30 KB RAM

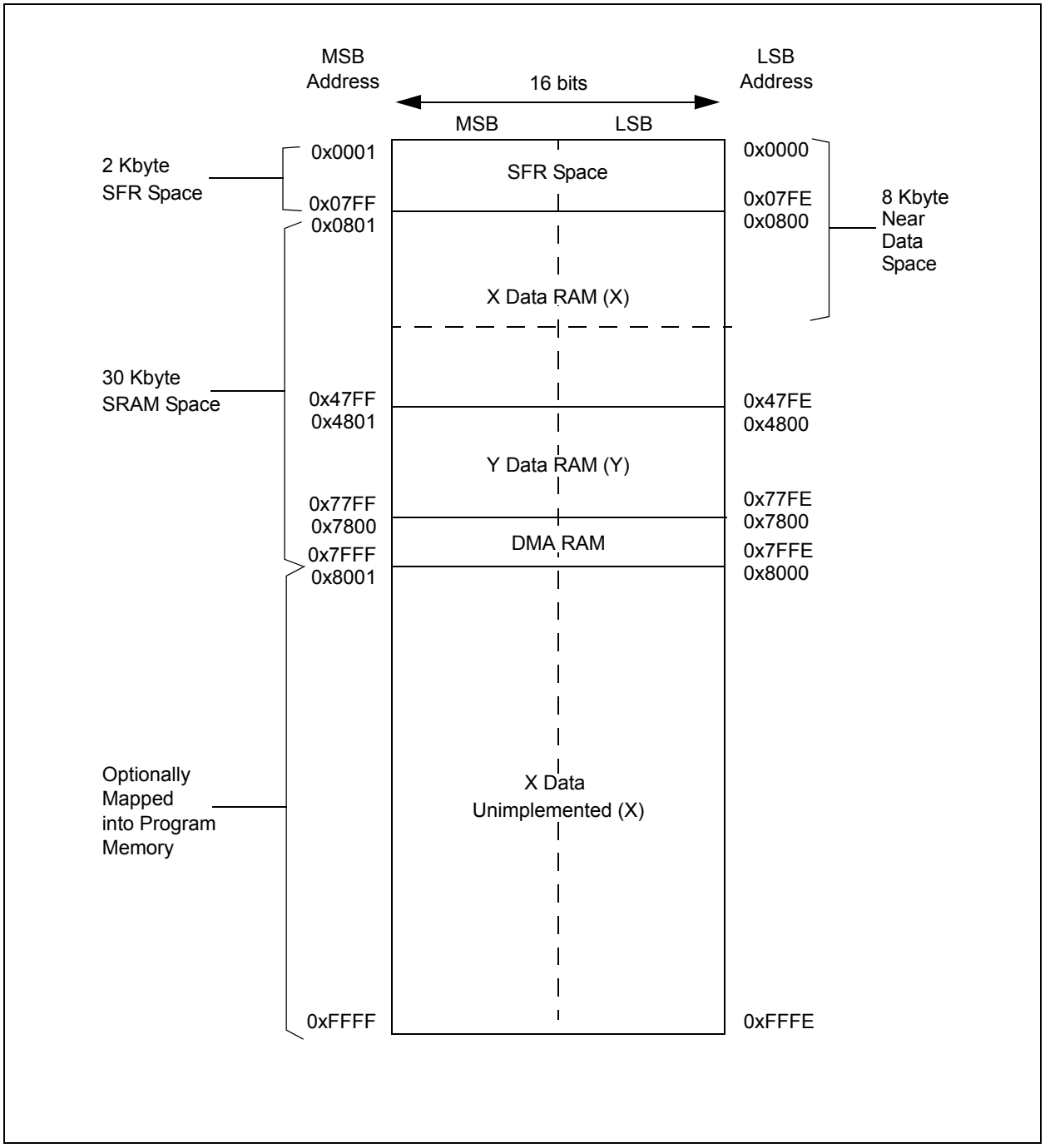


TABLE 4-36: FUNDAMENTAL ADDRESSING MODES SUPPORTED

Addressing Mode	Description
File Register Direct	The address of the file register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn forms the EA.
Register Indirect Post-Modified	The contents of Wn forms the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

4.3.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions and the DSP accumulator class of instructions provide a greater degree of addressing flexibility than other instructions. In addition to the Addressing modes supported by most MCU instructions, move and accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

Note: For the MOV instructions, the Addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit Wb (Register Offset) field is shared between both source and destination (but typically only used by one).

In summary, the following Addressing modes are supported by move and accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-modified
- Register Indirect Pre-modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-bit Literal
- 16-bit Literal

Note: Not all instructions support all the Addressing modes given above. Individual instructions may support different subsets of these Addressing modes.

4.3.4 MAC INSTRUCTIONS

The dual source operand DSP instructions (CLR, ED, EDAC, MAC, MPY, MPY.N, MOVSAC and MSC), also referred to as MAC instructions, utilize a simplified set of addressing modes to allow the user to effectively manipulate the data pointers through register indirect tables.

The 2-source operand prefetch registers must be members of the set {W8, W9, W10, W11}. For data reads, W8 and W9 are always directed to the X RAGU and W10 and W11 will always be directed to the Y AGU. The effective addresses generated (before and after modification) must, therefore, be valid addresses within X data space for W8 and W9 and Y data space for W10 and W11.

Note: Register Indirect with Register Offset Addressing mode is only available for W9 (in X space) and W11 (in Y space).

In summary, the following addressing modes are supported by the MAC class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.3.5 OTHER INSTRUCTIONS

Besides the various addressing modes outlined above, some instructions use literal constants of various sizes. For example, BRA (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the DISI instruction uses a 14-bit unsigned literal field. In some instructions, such as ADD Acc, the source of an operand or result is implied by the opcode itself. Certain operations, such as NOP, do not have any operands.

4.4 Modulo Addressing

Modulo Addressing mode is a method of providing an automated means to support circular data buffers using hardware. The objective is to remove the need for software to perform data address boundary checks when executing tightly looped code, as is typical in many DSP algorithms.

Modulo Addressing can operate in either data or program space (since the data pointer mechanism is essentially the same for both). One circular buffer can be supported in each of the X (which also provides the pointers into program space) and Y data spaces. Modulo Addressing

REGISTER 7-15: IPC0: INTERRUPT PRIORITY CONTROL REGISTER 0

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T1IP<2:0>			—	OC1IP<2:0>		
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	IC1IP<2:0>			—	INT0IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **T1IP<2:0>:** Timer1 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **OC1IP<2:0>:** Output Compare Channel 1 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **IC1IP<2:0>:** Input Capture Channel 1 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **INT0IP<2:0>:** External Interrupt 0 Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

9.0 OSCILLATOR CONFIGURATION

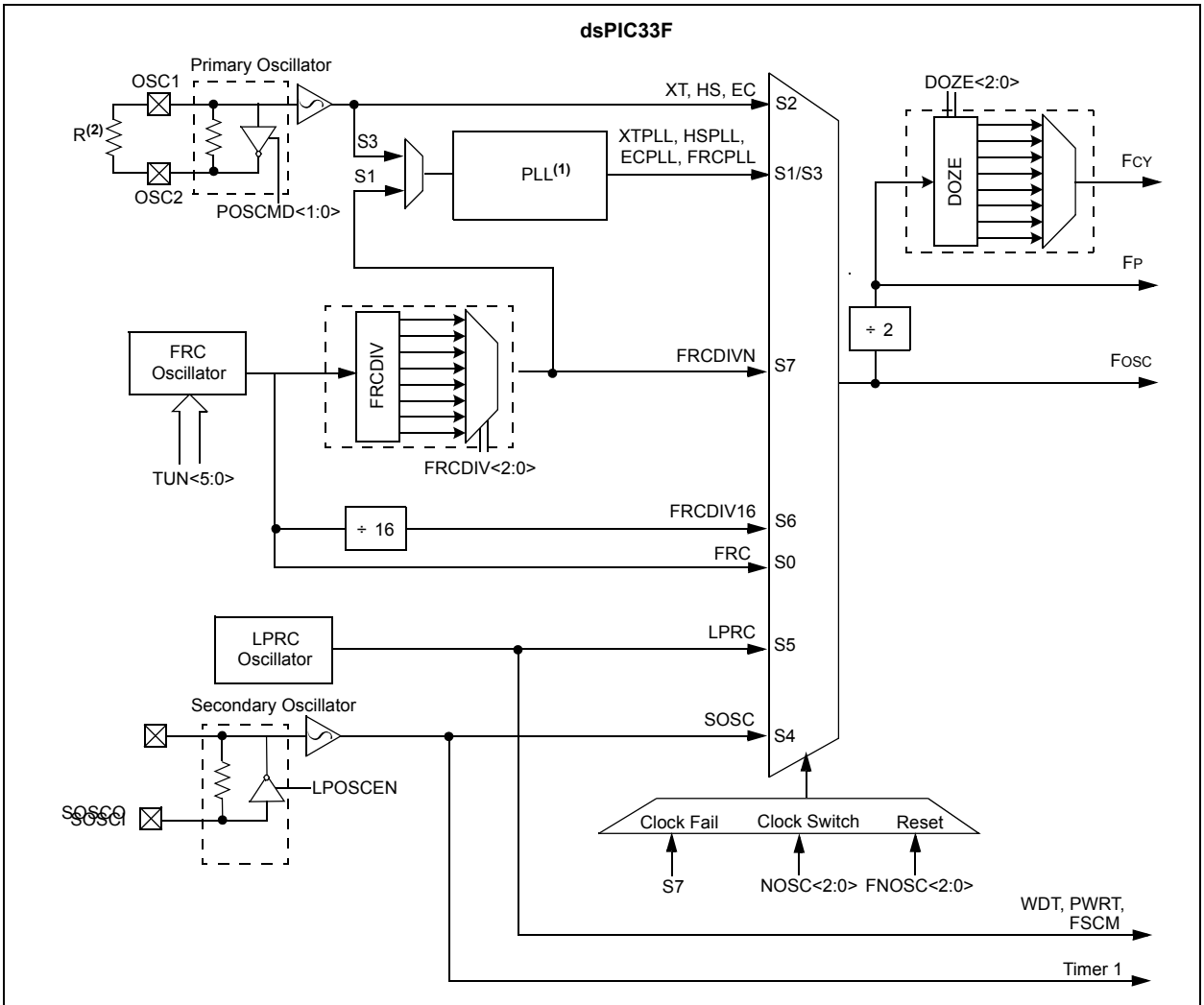
Note: This data sheet summarizes the features of the dsPIC33FJXXXMCX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 7. "Oscillator"** (DS70186) in the *"dsPIC33F Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The dsPIC33FJXXXMCX06/X08/X10 oscillator system provides the following:

- Various external and internal oscillator options as clock sources
- An on-chip PLL to scale the internal operating frequency to the required system clock frequency
- The internal FRC oscillator can also be used with the PLL, thereby allowing full-speed operation without any external clock generation hardware
- Clock switching between various clock sources
- Programmable clock postscaler for system power savings
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and takes fail-safe measures
- A Clock Control register (OSCCON)
- Nonvolatile Configuration bits for main oscillator selection

A simplified diagram of the oscillator system is shown in Figure 9-1.

FIGURE 9-1: dsPIC33FJXXXMCX06/X08/X10 OSCILLATOR SYSTEM DIAGRAM



Note 1: See Figure 9-2 for PLL details.
2: If the Oscillator is used with XT or HS modes, an extended parallel resistor with the value of 1 MΩ must be connected.

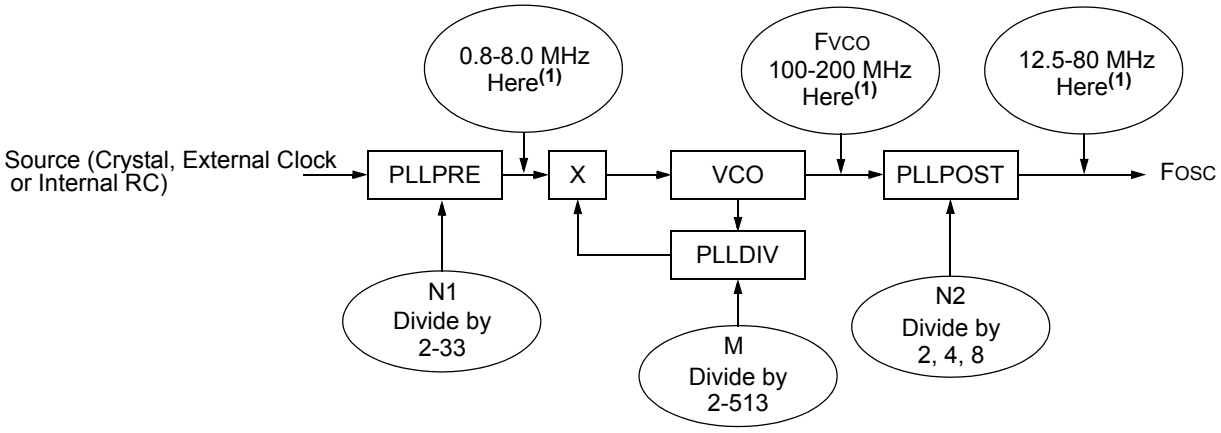
For example, suppose a 10 MHz crystal is being used with “XT with PLL” as the selected oscillator mode. If PLLPRE<4:0> = 0, then N1 = 2. This yields a VCO input of 10/2 = 5 MHz, which is within the acceptable range of 0.8-8 MHz. If PLLDIV<8:0> = 0x1E, then M = 32. This yields a VCO output of 5 * 32 = 160 MHz, which is within the 100-200 MHz ranged needed.

If PLLPOST<1:0> = 0, then N2 = 2. This provides a Fosc of 160/2 = 80 MHz. The resultant device operating speed is 80/2 = 40 MIPS.

EQUATION 9-3: XT WITH PLL MODE EXAMPLE

$$F_{CY} = \frac{F_{OSC}}{2} = \frac{1}{2}\left(\frac{10000000 \cdot 32}{2 \cdot 2}\right) = 40 \text{ MIPS}$$

FIGURE 9-2: dsPIC33FJXXXMCX06/X08/X10 PLL BLOCK DIAGRAM



Note 1: This frequency range must be satisfied at all times.

TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	Note
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	xx	111	**1, 2**
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	**1**
Low-Power RC Oscillator (LPRC)	Internal	xx	101	**1**
Secondary (Timer1) Oscillator (SOSC)	Secondary	xx	100	**1**
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011	**—**
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011	**—**
Primary Oscillator (EC) with PLL (ECPLL)	Primary	00	011	**1**
Primary Oscillator (HS)	Primary	10	010	**—**
Primary Oscillator (XT)	Primary	01	010	**—**
Primary Oscillator (EC)	Primary	00	010	**1**
Fast RC Oscillator with PLL (FRCPLL)	Internal	xx	001	**1**
Fast RC Oscillator (FRC)	Internal	xx	000	**1**

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

REGISTER 16-1: PxTCON: PWM TIME BASE CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
PTEN	—	PTSIDL	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTOPS<3:0>				PTCKPS<1:0>		PTMOD<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **PTEN:** PWM Time Base Timer Enable bit
1 = PWM time base is on
0 = PWM time base is off

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **PTSIDL:** PWM Time Base Stop in Idle Mode bit
1 = PWM time base halts in CPU Idle mode
0 = PWM time base runs in CPU Idle mode

bit 12-8 **Unimplemented:** Read as ‘0’

bit 7-4 **PTOPS<3:0>:** PWM Time Base Output Postscale Select bits
1111 = 1:16 postscale
•
•
•
0001 = 1:2 postscale
0000 = 1:1 postscale

bit 3-2 **PTCKPS<1:0>:** PWM Time Base Input Clock Prescale Select bits
11 = PWM time base input clock period is 64 TCY (1:64 prescale)
10 = PWM time base input clock period is 16 TCY (1:16 prescale)
01 = PWM time base input clock period is 4 TCY (1:4 prescale)
00 = PWM time base input clock period is TCY (1:1 prescale)

bit 1-0 **PTMOD<1:0>:** PWM Time Base Mode Select bits
11 = PWM time base operates in a Continuous Up/Down Count mode with interrupts for double PWM updates
10 = PWM time base operates in a Continuous Up/Down Count mode
01 = PWM time base operates in Single Pulse mode
00 = PWM time base operates in a Free-Running mode

18.0 SERIAL PERIPHERAL INTERFACE (SPI)

Note: This data sheet summarizes the features of the dsPIC33FJXXXMCX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 18. "Serial Peripheral Interface (SPI)"** (DS70206) in the *"dsPIC33F Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The Serial Peripheral Interface (SPI) module is a synchronous serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, ADC, etc. The SPI module is compatible with SPI and SIOP from Motorola®.

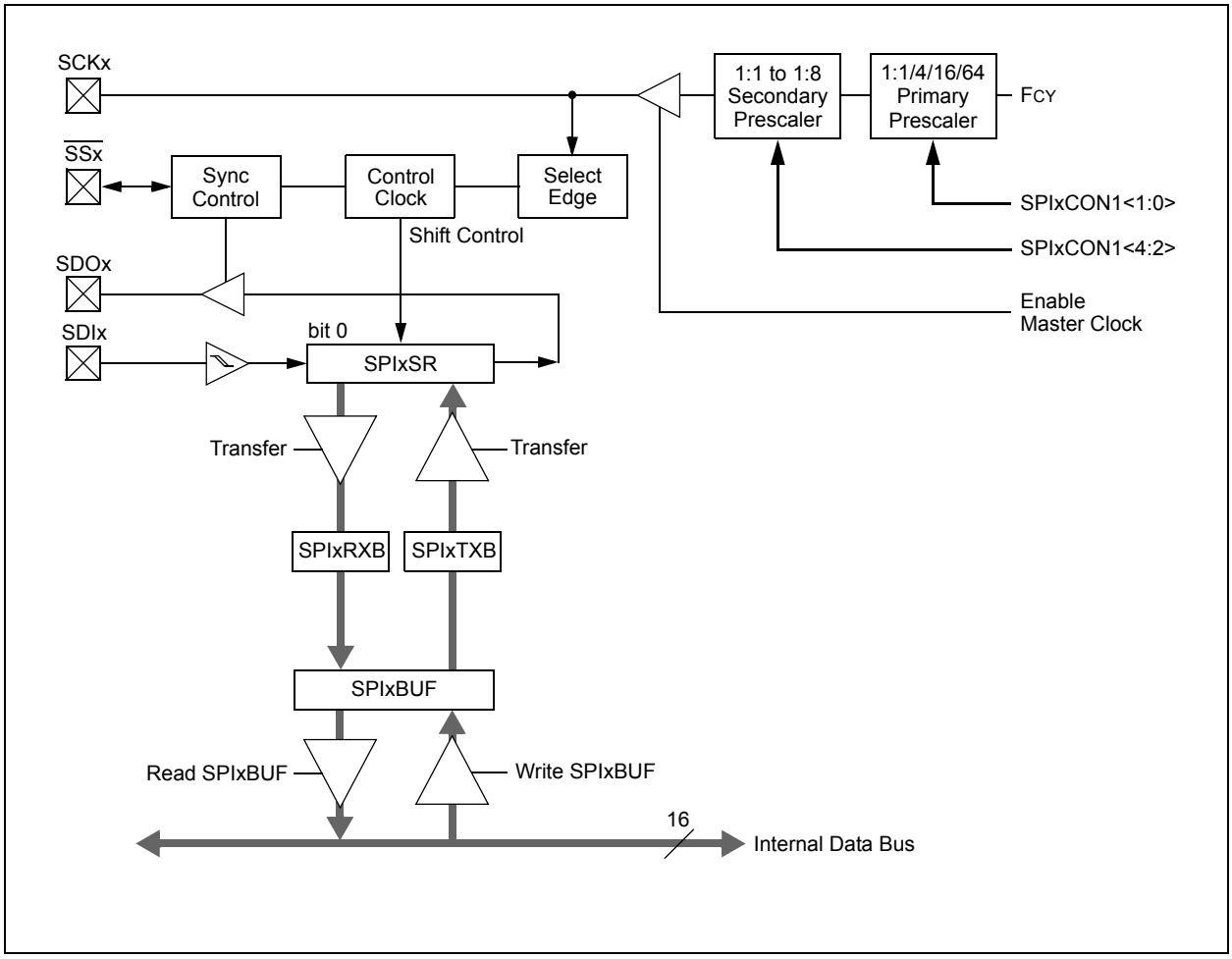
Note: In this section, the SPI modules are referred to together as SPIx, or separately as SPI1 and SPI2. Special Function Registers will follow a similar notation. For example, SPIxCON refers to the control register for the SPI1 or SPI2 module.

Each SPI module consists of a 16-bit shift register, SPIxSR (where x = 1 or 2), used for shifting data in and out, and a buffer register, SPIxBUF. A control register, SPIxCON, configures the module. Additionally, a status register, SPIxSTAT, indicates various status conditions.

The serial interface consists of 4 pins: SDIx (serial data input), SDOx (serial data output), SCKx (shift clock input or output) and $\overline{SSx}$ (active-low slave select).

In Master mode operation, SCK is a clock output, but in Slave mode, it is a clock input.

FIGURE 18-1: SPI MODULE BLOCK DIAGRAM



20.0 UNIVERSAL ASYNCHRONOUS RECEIVER TRANSMITTER (UART)

Note: This data sheet summarizes the features of the dsPIC33FJXXXMCX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 17. "UART"** (DS70188) in the *"dsPIC33F Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The Universal Asynchronous Receiver Transmitter (UART) module is one of the serial I/O modules available in the dsPIC33FJXXXMCX06/X08/X10 device family. The UART is a full-duplex asynchronous system that can communicate with peripheral devices, such as personal computers, LIN, RS-232 and RS-485 interfaces. The module also supports a hardware flow control option with the $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins and also includes an IrDA® encoder and decoder.

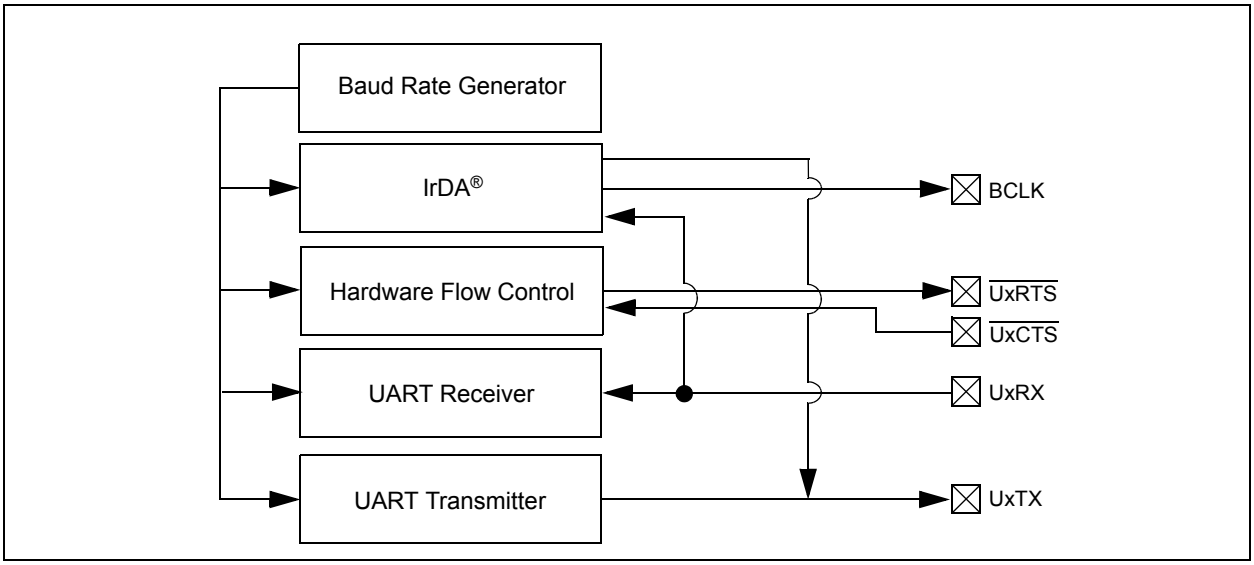
The primary features of the UART module are:

- Full-Duplex, 8-bit or 9-bit Data Transmission through the UxTX and UxRX pins
- Even, Odd or No Parity Options (for 8-bit data)
- One or Two Stop bits
- Hardware Flow Control Option with $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins
- Fully Integrated Baud Rate Generator with 16-bit Prescaler
- Baud rates ranging from 1 Mbps to 15 bps at 16x mode at 40 MIPS
- Baud rates ranging from 4 Mbps to 61 bps at 4x mode at 40 MIPS
- 4-deep First-In-First-Out (FIFO) Transmit Data Buffer
- 4-Deep FIFO Receive Data Buffer
- Parity, Framing and Buffer Overrun Error Detection
- Support for 9-bit mode with Address Detect (9th bit = 1)
- Transmit and Receive Interrupts
- A Separate Interrupt for all UART Error Conditions
- Loopback mode for Diagnostic Support
- Support for Sync and Break Characters
- Supports Automatic Baud Rate Detection
- IrDA® Encoder and Decoder Logic
- 16x Baud Clock Output for IrDA® Support

A simplified block diagram of the UART is shown in Figure 20-1. The UART module consists of the key important hardware elements:

- Baud Rate Generator
- Asynchronous Transmitter
- Asynchronous Receiver

FIGURE 20-1: UART SIMPLIFIED BLOCK DIAGRAM



Note 1: Both UART1 and UART2 can trigger a DMA data transfer. If U1TX, U1RX, U2TX or U2RX is selected as a DMA IRQ source, a DMA transfer occurs when the U1TXIF, U1RXIF, U2TXIF or U2RXIF bit gets set as a result of a UART1 or UART2 transmission or reception.

2: If DMA transfers are required, the UART TX/RX FIFO buffer must be set to a size of 1 byte/word (i.e., UTXISEL<1:0> = 00 and URXISEL<1:0> = 00).

22.0 10-BIT/12-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

Note:	This data sheet summarizes the features of the dsPIC33FJXXXMCX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The dsPIC33FJXXXMCX06/X08/X10 devices have up to 32 ADC input channels. These devices also have up to 2 ADC modules (ADCx, where 'x' = 1 or 2), each with its own set of Special Function Registers.

The AD12B bit (ADxCON1<10>) allows each of the ADC modules to be configured by the user as either a 10-bit, 4-sample/hold ADC (default configuration) or a 12-bit, 1-sample/hold ADC.

Note:	The ADC module needs to be disabled before modifying the AD12B bit.

22.1 Key Features

The 10-bit ADC configuration has the following key features:

- Successive Approximation (SAR) conversion
- Conversion speeds of up to 1.1 Msps
- Up to 32 analog input pins
- External voltage reference input pins
- Simultaneous sampling of up to four analog input pins
- Automatic Channel Scan mode
- Selectable conversion trigger source
- Selectable Buffer Fill modes
- Four result alignment options (signed/unsigned, fractional/integer)
- Operation during CPU Sleep and Idle modes

The 12-bit ADC configuration supports all the above features, except:

- In the 12-bit configuration, conversion speeds of up to 500 ksps are supported
- There is only 1 sample/hold amplifier in the 12-bit configuration, so simultaneous sampling of multiple channels is not supported.

Depending on the particular device pinout, the ADC can have up to 32 analog input pins, designated AN0 through AN31. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins. The actual number of analog input pins and external voltage reference input configuration will depend on the specific device. Refer to the device data sheet for further details.

A block diagram of the ADC is shown in Figure 22-1.

22.2 ADC Initialization

The following configuration steps should be performed.

1. Configure the ADC module:
   a) Select port pins as analog inputs (ADxPCFGH<15:0> or ADxPCFGL<15:0>)
   b) Select voltage reference source to match expected range on analog inputs (ADxCON2<15:13>)
   c) Select the analog conversion clock to match desired data rate with processor clock (ADxCON3<7:0>)
   d) Determine how many S/H channels will be used (ADxCON2<9:8> and ADxPCFGH<15:0> or ADxPCFGL<15:0>)
   e) Select the appropriate sample/conversion sequence (ADxCON1<7:5> and ADxCON3<12:8>)
   f) Select how conversion results are presented in the buffer (ADxCON1<9:8>)
   g) Turn on ADC module (ADxCON1<15>)
2. Configure ADC interrupt (if required):
   a) Clear the ADxIF bit
   b) Select ADC interrupt priority

22.3 ADC and DMA

If more than one conversion result needs to be buffered before triggering an interrupt, DMA data transfers can be used. Both ADC1 and ADC2 can trigger a DMA data transfer. If ADC1 or ADC2 is selected as the DMA IRQ source, a DMA transfer occurs when the AD1IF or AD2IF bit gets set as a result of an ADC1 or ADC2 sample conversion sequence.

The SMPI<3:0> bits (ADxCON2<5:2>) are used to select how often the DMA RAM buffer pointer is incremented.

The ADDMABM bit (ADxCON1<12>) determines how the conversion results are filled in the DMA RAM buffer area being used for ADC. If this bit is set, DMA buffers are written in the order of conversion. The module will provide an address to the DMA channel that is the same as the address used for the non-DMA stand-alone buffer. If the ADDMABM bit is cleared, then DMA buffers are written in Scatter/Gather mode. The module will provide a scatter/gather address to the DMA channel, based on the index of the analog input and the size of the DMA buffer.

23.4 Watchdog Timer (WDT)

For dsPIC33FJXXXMCX06/X08/X10 devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler than can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a nominal WDT time-out period (TWDT) of 1 ms in 5-bit mode, or 4 ms in 7-bit mode.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>) which allow the selection of a total of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSC bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

If the WDT is enabled, it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake the device and code execution will continue from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bits (RCON<3,2>) will need to be cleared in software after the device wakes up.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

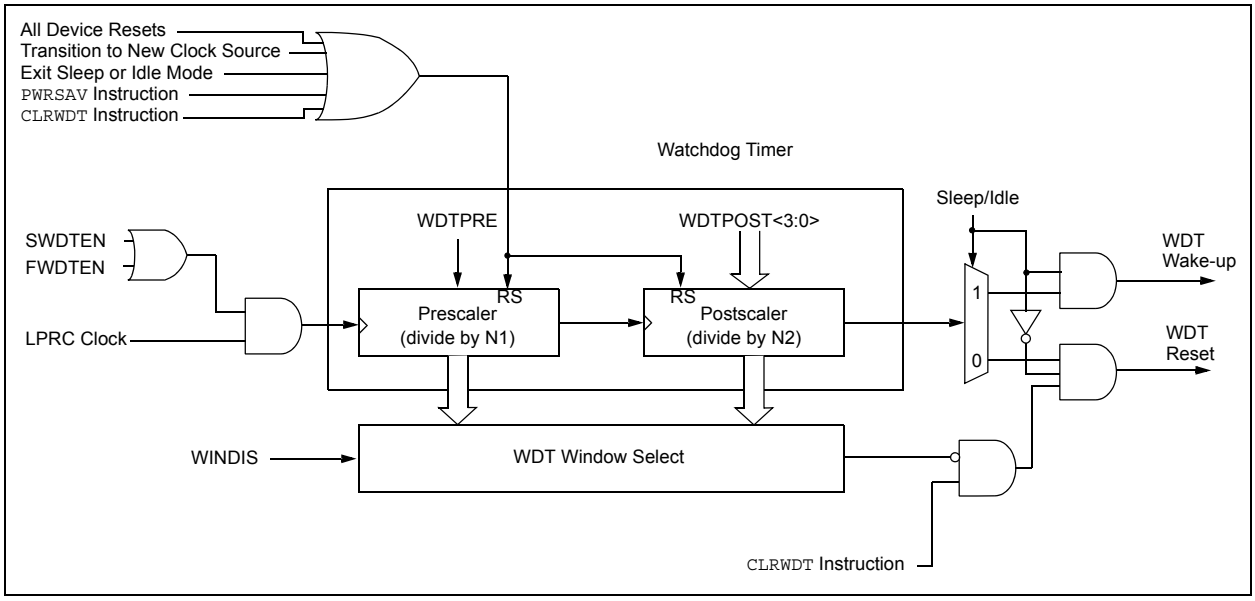
Note: The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDT Configuration register. When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to '0'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

Note: If the WINDIS bit (FWDT<6>) is cleared, the CLRWDT instruction should be executed by the application software only during the last 1/4 of the WDT period. This CLRWDT window can be determined by using a timer. If a CLRWDT instruction is executed before this window, a WDT Reset occurs.

FIGURE 23-2: WDT BLOCK DIAGRAM



All instructions are a single word, except for certain double-word instructions, which were made double-word instructions so that all the required information is available in these 48 bits. In the second word, the 8 MSbs are '0's. If this second word is executed as an instruction (by itself), it will execute as a NOP.

Most single-word instructions are executed in a single instruction cycle, unless a conditional test is true, or the program counter is changed as a result of the instruction. In these cases, the execution takes two instruction cycles with the additional instruction cycle(s) executed as a NOP. Notable exceptions are the BRA (unconditional/computed branch), indirect CALL/GOTO, all table reads and writes and RETURN/RETFIE instructions, which are single-word instructions but take two or three cycles. Certain instructions that involve skipping over the subsequent instruction require either two or three cycles if the skip is performed, depending on whether the instruction being skipped is a single-word or two-word instruction. Moreover, double-word moves require two cycles. The double-word instructions execute in two instruction cycles.

Note: For more details on the instruction set, refer to the *"dsPIC30F/33F Programmer's Reference Manual"* (DS70157).

TABLE 24-1: SYMBOLS USED IN OPCODE DESCRIPTIONS

Field	Description
#text	Means literal defined by "text"
(text)	Means "content of text"
[text]	Means "the location addressed by text"
{ }	Optional field or operation
<n:m>	Register bit field
.b	Byte mode selection
.d	Double-Word mode selection
.S	Shadow register select
.w	Word mode selection (default)
Acc	One of two accumulators {A, B}
AWB	Accumulator write back destination address register ∈ {W13, [W13]+ = 2}
bit4	4-bit bit selection field (used in word addressed instructions) ∈ {0...15}
C, DC, N, OV, Z	MCU Status bits: Carry, Digit Carry, Negative, Overflow, Sticky Zero
Expr	Absolute address, label or expression (resolved by the linker)
f	File register address ∈ {0x0000...0x1FFF}
lit1	1-bit unsigned literal ∈ {0,1}
lit4	4-bit unsigned literal ∈ {0...15}
lit5	5-bit unsigned literal ∈ {0...31}
lit8	8-bit unsigned literal ∈ {0...255}
lit10	10-bit unsigned literal ∈ {0...255} for Byte mode, {0:1023} for Word mode
lit14	14-bit unsigned literal ∈ {0...16384}
lit16	16-bit unsigned literal ∈ {0...65535}
lit23	23-bit unsigned literal ∈ {0...8388608}; LSb must be '0'
None	Field does not require an entry, may be blank
OA, OB, SA, SB	DSP Status bits: AccA Overflow, AccB Overflow, AccA Saturate, AccB Saturate
PC	Program Counter
Slit10	10-bit signed literal ∈ {-512...511}
Slit16	16-bit signed literal ∈ {-32768...32767}
Slit6	6-bit signed literal ∈ {-16...16}
Wb	Base W register ∈ {W0..W15}
Wd	Destination W register ∈ { Wd, [Wd], [Wd++], [Wd--], [++Wd], [--Wd] }
Wdo	Destination W register ∈ { Wnd, [Wnd], [Wnd++], [Wnd--], [++Wnd], [--Wnd], [Wnd+Wb] }
Wm,Wn	Dividend, Divisor working register pair (direct addressing)
Wm*Wm	Multiplicand and Multiplier working register pair for Square instructions ∈ {W4 * W4,W5 * W5,W6 * W6,W7 * W7}

25.2 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for all PIC MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

25.3 MPLAB C18 and MPLAB C30 C Compilers

The MPLAB C18 and MPLAB C30 Code Development Systems are complete ANSI C compilers for Microchip's PIC18 and PIC24 families of microcontrollers and the dsPIC30 and dsPIC33 family of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use not found with other compilers.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

25.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

25.5 MPLAB ASM30 Assembler, Linker and Librarian

MPLAB ASM30 Assembler produces relocatable machine code from symbolic assembly language for dsPIC30F devices. MPLAB C30 C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire dsPIC30F instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

25.6 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C18 and MPLAB C30 C Compilers, and the MPASM and MPLAB ASM30 Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

TABLE 26-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

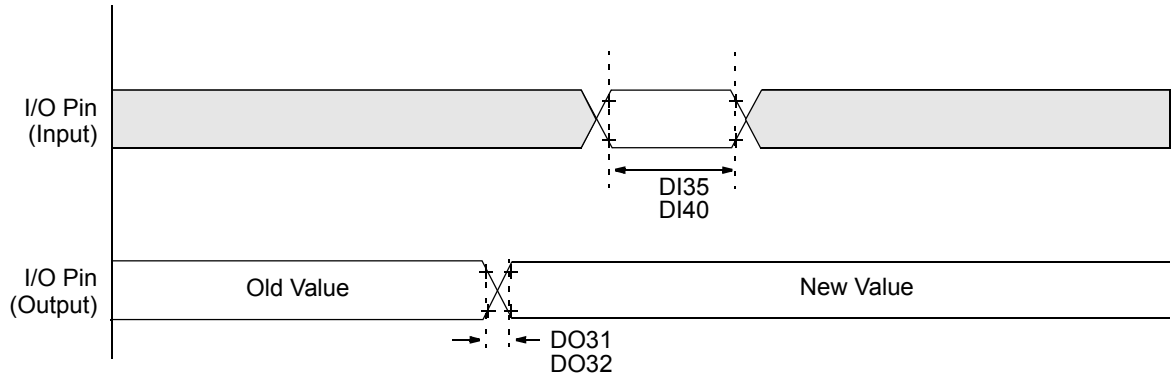
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
	VOL	**Output Low Voltage**					
DO10		I/O ports	—	—	0.4	V	IOL = 2mA, VDD = 3.3V
DO16		OSC2/CLKO	—	—	0.4	V	IOL = 2mA, VDD = 3.3V
	VOH	**Output High Voltage**					
DO20		I/O ports	2.40	—	—	V	IOH = -2.3 mA, VDD = 3.3V
DO26		OSC2/CLKO	2.41	—	—	V	IOH = -1.3 mA, VDD = 3.3V

TABLE 26-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param No.	Symbol	Characteristic	Min(1)	Typ	Max(1)	Units	Conditions
BO10	VBOR	BOR Event on VDD transition high-to-low BOR event is tied to VDD core voltage decrease	2.40	—	2.55	V	—

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

FIGURE 26-3: CLKO AND I/O TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-20: I/O TIMING REQUIREMENTS

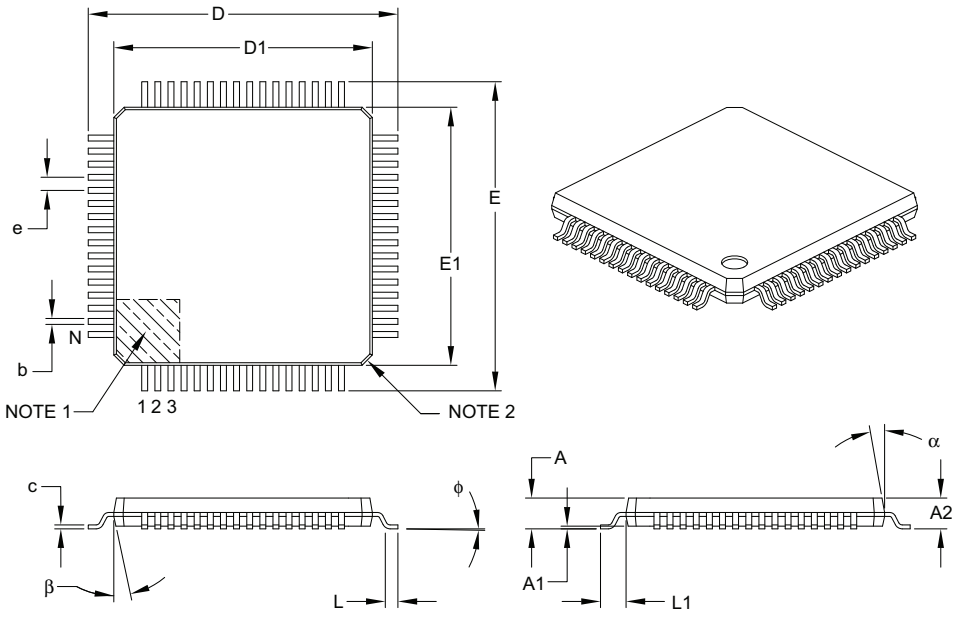
AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	10	25	ns	—
DO32	TIOF	Port Output Fall Time	—	10	25	ns	—
DI35	TINP	INTx Pin High or Low Time (output)	20	—	—	ns	—
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	—

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

27.2 Package Details

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

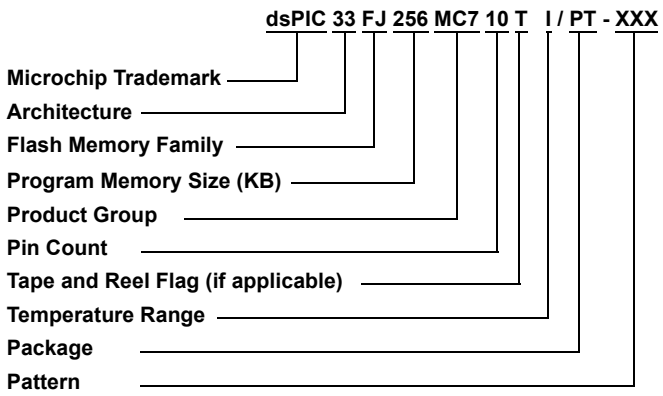
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Architecture:	33	=	16-bit Digital Signal Controller
Flash Memory Family:	FJ	=	Flash program memory, 3.3V
Product Group:	MC5	=	Motor Control family
	MC7	=	Motor Control family
Pin Count:	06	=	64-pin
	08	=	80-pin
	10	=	100-pin
Temperature Range:	I	=	-40°C to +85°C (Industrial)
Package:	PT	=	10x10 or 12x12 mm TQFP (Thin Quad Flatpack)
	PF	=	14x14 mm TQFP (Thin Quad Flatpack)
Pattern	Three-digit QTP, SQTP, Code or Special Requirements (blank otherwise)		

Examples:

a) dsPIC33FJ64MC706I/PT:
Motor Control dsPIC33, 64 KB program memory, 64-pin, Industrial temp., TQFP package.